

# 03P4MG,03P6MG

# 300 mA HIGH-WITHSTANDING-VOLTAGE MOLD SCR

#### **DESCRIPTION**

The 03P4MG and 03P6MG are P-gate fully diffused mold SCRs with an average on-state current of 300 mA. The repeat peak off-state voltages (and reverse voltages) are 400 and 600 V.

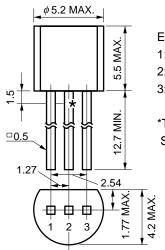
#### **FEATURES**

- 400 and 600 V high-withstanding-voltage series of products
- The non-repetitive withstanding voltage is a high 700 V, making it easy to harmonize the rise voltage of the surge absorber.
- High-sensitivity thyristor (Igt = 3 to 50  $\mu$ A)
- Employs flame-retardant epoxy resin (UL94V-0)

#### **APPLICATIONS**

Leakage breakers, SSRs, various type of alarms, consumer electronic equipments and automobile electronic components

## PACKAGE DRAWING (Unit: mm)



Electrode connection

- 1: Gate
- 2: Anode
- 3: Cathode

\*Tc test bench-mark Standard weight: 0.3 g

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C)

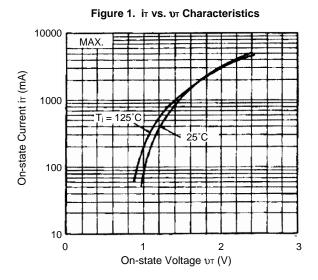
	Parameter	Symbol	Ratings			Remarks
			03P4MG	03P6MG		
-	Non-repetitive Peak Reverse Voltage	Vrsm	700	700	V	$R_{GK} = 1 k\Omega$
	Non-repetitive Peak Off-state Voltage	VDSM	700	700	V	$R_{GK} = 1 k\Omega$
	Repetitive Peak Reverse Voltage	VRRM	400	600	V	$R_{GK} = 1 k\Omega$
	Repetitive Peak Off-state Voltage	VDRM	400	600	V	$R_{GK} = 1 k\Omega$
	Average On-state Current	I <sub>T(AV)</sub>	300 (T <sub>A</sub> = 30°C, Single half-wave, $\theta$ = 180°)			Refer to Figure 10.
	Effective On-state Current	I <sub>T(RMS)</sub>	470			_
	Surge On-state Current	Ітѕм	8 (f = 50 Hz, Sine half-wave, 1 cycle)			Refer to Figure 2.
	Fusing Current	∫i⊤²dt	0.15 (1 ms ≤ t ≤ 10 ms)			-
	Critical Rate of On-state Current of Rise	dl⊤/dt	20			_
	Peak Gate Power Dissipation	Рсм	100 (f ≥ 50 Hz, Duty ≤ 10%)			Refer to Figure 3.
	Average Gate Power Dissipation	P <sub>G(AV)</sub>	10			Refer to Figure 3.
	Peak Gate Forward Current	Iгдм	100 (f ≥ 50 Hz, Duty ≤ 10%)			_
	Peak Gate Reverse Voltage	Vrgm	6		V	_
	Junction Temperature	Tj	-40 to	°C	_	
	Storage Temperature	Tstg	-55 to +150			_

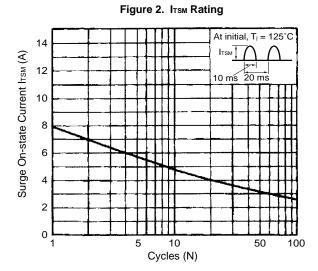
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ELECTRICAL CHARACTERISTICS ( $T_j = 25$ °C,  $R_{GK} = 1 \text{ k}\Omega$ )

Parameter	Symbol	Conditions		Specifications			Unit	Remarks
				MIN.	TYP.	MAX.		
Non-repetitive Peak Reverse	IRRM	V <sub>RM</sub> = V <sub>RRM</sub>	$T_j = 25^{\circ}C$	_	_	10	μΑ	_
Current			T <sub>j</sub> = 125°C	-	_	100	μΑ	_
Non-repetitive Peak Off-state	IDRM	VDM = VDRM	$T_j = 25^{\circ}C$	_	_	10	μΑ	_
Current			T <sub>j</sub> = 125°C	_	_	100	μΑ	_
Critical Rate-of-rise of Off-state	dV⊳/dt	$T_{j} = 125^{\circ}C, V_{DM} = \frac{2}{3}V_{DRM}$		10	_	_	V/μs	-
Voltage								
On-state Voltage	VT	Iτ = 4 A		_	_	2.2	V	Refer to Figure 1.
Gate Trigger Current	lgт	$V_{DM} = 6 \text{ V, } R_{L} = 100 \ \Omega$ $V_{DM} = 6 \text{ V, } R_{L} = 100 \ \Omega$ $T_{j} = 125^{\circ}\text{C, } V_{DM} = \frac{V_{DRM}}{2}$ $V_{DM} = 24 \text{ V, } I_{TM} = 4 \text{ A}$		3	_	50	μΑ	_
Gate Trigger Voltage	Vgт			_	_	0.8	V	_
Gate Non-trigger Voltage	V <sub>GD</sub>			0.2	_	_	V	_
Holding Current	lн			_	_	5	mA	-
Turn-off Time	tq	$T_{j} = 125^{\circ}C$ , $I_{T} = 200 \text{ mA}$ , $I_{R}/I_{R} = 15 \text{ A}/\mu\text{s}$ , $I_{R} \ge 25 \text{ V}$ ,		-	60	_	μs	_
		$V_{DM} = \frac{2}{3} V_{DRM}, dV_{D}/$						
, , ,		Junction-to-case D	-	_	50	°C/W	Refer to Figure 14.	
		Junction-to-ambier	-ambient DC		_	230	°C/W	Refer to Figure 14.

# TYPICAL CHARACTERISTICS (TA = 25°C)





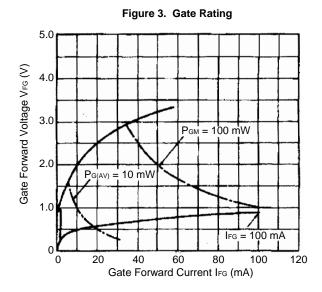


Figure 4. Example of Gate Characteristics Gate Trigger Voltage Vg⊤ (V) 1.0 0°C 8.0 0.6 0.4 0.2 0 0 50 100 150 200 300 350 250 Gate Trigger Current Igt (µA)

Figure 5. Igt vs. TA Example of Characteristics

100 Sate Trigger Current lc⊤ (µA) 10 0.1 20 40 60 80 100 120 140 Ambient Temperature T<sub>A</sub> (°C)

Figure 6. Vgt vs. TA Example of Characteristics

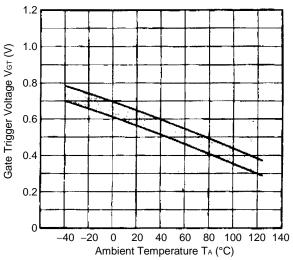


Figure 7. ics vs. τ Example of Characteristics

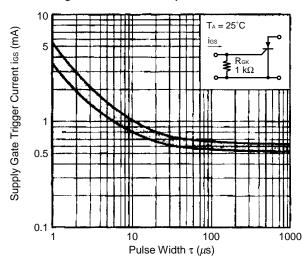


Figure 8. υστ vs. τ Example of Characteristics

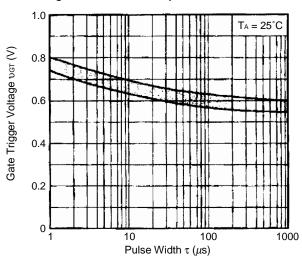


Figure 9. PT(AV) vs. IT(AV) Characteristics

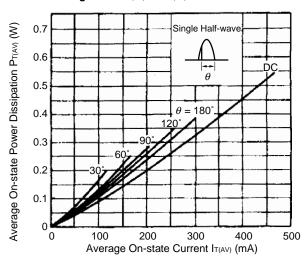


Figure 10. TA vs. IT(AV) Characteristics

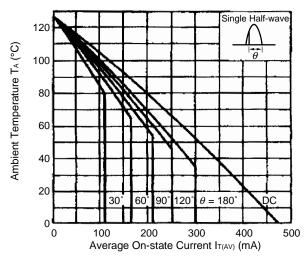


Figure 11. PT(AV) vs. IT(AV) Characteristics

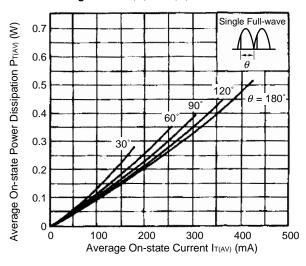


Figure 12. TA vs. IT(AV) Characteristics

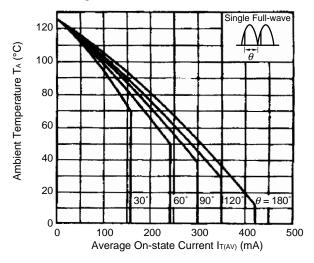
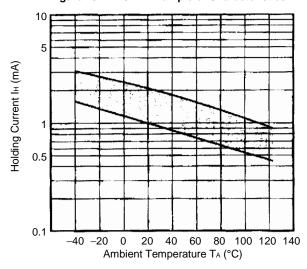


Figure 13. In vs. TA Example of Characteristics



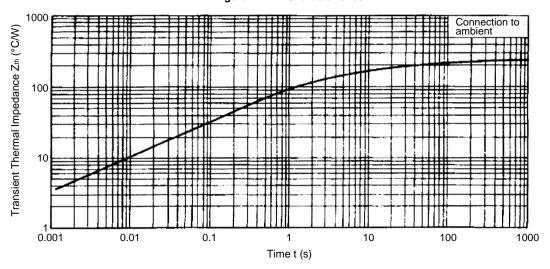


Figure 14. Zth Characteristics

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